

PCN #: 06_0126**Title:**

DAC8412/3 redesign and fab process change.

Date Published:

November 3, 2006

Type:

Device

Part Number:

DAC8412/3

Proposed Change:

ADI sent customers an advance PCN (05_0126 dated December 23, 2005) outlining plans to transfer processes from ADI's Silicon Valley, California Fab/Trim/Probe facilities (ADSiV) to other internal ADI facilities. This PCN (06_0126) specifically addresses plans to redesign and transfer the DAC8412/3 commercial devices from the LVCMOS wafer fab process at ADSiV to the H6 wafer fab process at Analog Devices, Limerick, Ireland.

Data sheet specifications are changing as follows:

From: For single supply operation only ($V_{refl}=0.0V$, $V_{ss}=0.0V$): Due to internal offset errors, INL and DNL are measured beginning at code 2 (002H).

To: For single supply operation only ($V_{refl}=0.0V$, $V_{ss}=0.0V$): Due to internal offset errors, INL and DNL are measured beginning at code 5 (005H).

Reason for Change:

As detailed in PCN 05_0126, ADI is consolidating front-end manufacturing operations. Quality and reliability levels and package dimensions are not affected by these changes. The DAC8412/3 will have comparable or improved manufacturing capabilities.

Summary of Supporting Information:

1. The Limerick facility is certified to all major quality, environmental, health and safety systems (including ISO9001:2000, ISO14001:2004, ISO/TS16949:2002, OHSAS 18001:1999 and MIL-PRF-38535).
2. Reliability report number, RQR03601, is available upon request.

Planned Date Change Effective:

February 1, 2007

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